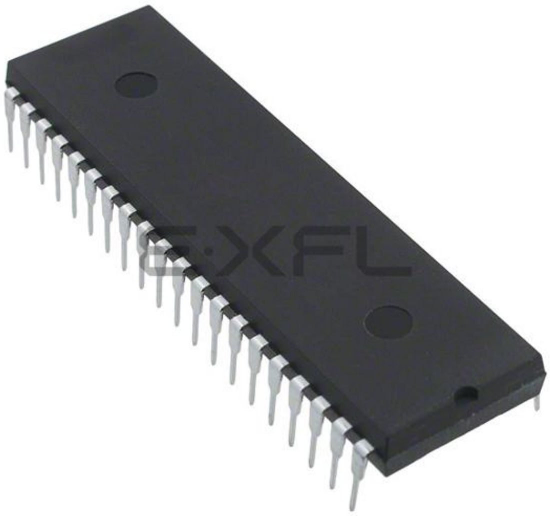

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Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf874-04i-p

TABLE 1-2: PIC16F874 AND PIC16F877 PINOUT DESCRIPTION

Pin Name	DIP Pin#	PLCC Pin#	QFP Pin#	I/O/P Type	Buffer Type	Description
OSC1/CLKIN	13	14	30	I	ST/CMOS(4)	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	14	15	31	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
$\overline{MCLR}$/VPP	1	2	18	I/P	ST	Master Clear (Reset) input or programming voltage input. This pin is an active low RESET to the device.
						PORTA is a bi-directional I/O port.
RA0/AN0	2	3	19	I/O	TTL	RA0 can also be analog input0.
RA1/AN1	3	4	20	I/O	TTL	RA1 can also be analog input1.
RA2/AN2/VREF-	4	5	21	I/O	TTL	RA2 can also be analog input2 or negative analog reference voltage.
RA3/AN3/VREF+	5	6	22	I/O	TTL	RA3 can also be analog input3 or positive analog reference voltage.
RA4/T0CKI	6	7	23	I/O	ST	RA4 can also be the clock input to the Timer0 timer/counter. Output is open drain type.
RA5/$\overline{SS}$/AN4	7	8	24	I/O	TTL	RA5 can also be analog input4 or the slave select for the synchronous serial port.
						PORTB is a bi-directional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs.
RB0/INT	33	36	8	I/O	TTL/ST(1)	RB0 can also be the external interrupt pin.
RB1	34	37	9	I/O	TTL	
RB2	35	38	10	I/O	TTL	
RB3/PGM	36	39	11	I/O	TTL	RB3 can also be the low voltage programming input.
RB4	37	41	14	I/O	TTL	Interrupt-on-change pin.
RB5	38	42	15	I/O	TTL	Interrupt-on-change pin.
RB6/PGC	39	43	16	I/O	TTL/ST(2)	Interrupt-on-change pin or In-Circuit Debugger pin. Serial programming clock.
RB7/PGD	40	44	17	I/O	TTL/ST(2)	Interrupt-on-change pin or In-Circuit Debugger pin. Serial programming data.

Legend: I = input O = output I/O = input/output P = power
— = Not used TTL = TTL input ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured as an external interrupt.
2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.
3: This buffer is a Schmitt Trigger input when configured as general purpose I/O and a TTL input when used in the Parallel Slave Port mode (for interfacing to a microprocessor bus).
4: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

2.2.2.1 STATUS Register

The STATUS register contains the arithmetic status of the ALU, the RESET status and the bank select bits for data memory.

The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are not writable, therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper three bits and set the Z bit. This leaves the STATUS register as `000u u1uu` (where `u` = unchanged).

It is recommended, therefore, that only `BCF`, `BSF`, `SWAPF` and `MOVWF` instructions are used to alter the STATUS register, because these instructions do not affect the Z, C or DC bits from the STATUS register. For other instructions not affecting any status bits, see the "Instruction Set Summary."

> **Note:** The C and DC bits operate as a $\overline{\text{borrow}}$ and $\overline{\text{digit borrow}}$ bit, respectively, in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

REGISTER 2-1: STATUS REGISTER (ADDRESS 03h, 83h, 103h, 183h)

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
IRP	RP1	RP0	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C
bit 7							bit 0

bit 7 **IRP:** Register Bank Select bit (used for indirect addressing)
`1` = Bank 2, 3 (100h - 1FFh)
`0` = Bank 0, 1 (00h - FFh)

bit 6-5 **RP1:RP0**: Register Bank Select bits (used for direct addressing)
`11` = Bank 3 (180h - 1FFh)
`10` = Bank 2 (100h - 17Fh)
`01` = Bank 1 (80h - FFh)
`00` = Bank 0 (00h - 7Fh)
Each bank is 128 bytes

bit 4 **$\overline{\text{TO}}$**: Time-out bit
`1` = After power-up, `CLRWDT` instruction, or `SLEEP` instruction
`0` = A WDT time-out occurred

bit 3 **$\overline{\text{PD}}$**: Power-down bit
`1` = After power-up or by the `CLRWDT` instruction
`0` = By execution of the `SLEEP` instruction

bit 2 **Z**: Zero bit
`1` = The result of an arithmetic or logic operation is zero
`0` = The result of an arithmetic or logic operation is not zero

bit 1 **DC**: Digit carry/$\overline{\text{borrow}}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)
(for $\overline{\text{borrow}}$, the polarity is reversed)
`1` = A carry-out from the 4th low order bit of the result occurred
`0` = No carry-out from the 4th low order bit of the result

bit 0 **C**: Carry/$\overline{\text{borrow}}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)
`1` = A carry-out from the Most Significant bit of the result occurred
`0` = No carry-out from the Most Significant bit of the result occurred

> **Note:** For $\overline{\text{borrow}}$, the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high, or low order bit of the source register.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

3.0 I/O PORTS

Some pins for these I/O ports are multiplexed with an alternate function for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

Additional information on I/O ports may be found in the PIC® MCU Mid-Range Reference Manual, (DS33023).

3.1 PORTA and the TRISA Register

PORTA is a 6-bit wide, bi-directional port. The corresponding data direction register is TRISA. Setting a TRISA bit (= 1) will make the corresponding PORTA pin an input (i.e., put the corresponding output driver in a Hi-Impedance mode). Clearing a TRISA bit (= 0) will make the corresponding PORTA pin an output (i.e., put the contents of the output latch on the selected pin).

Reading the PORTA register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, the value is modified and then written to the port data latch.

Pin RA4 is multiplexed with the Timer0 module clock input to become the RA4/T0CKI pin. The RA4/T0CKI pin is a Schmitt Trigger input and an open drain output. All other PORTA pins have TTL input levels and full CMOS output drivers.

Other PORTA pins are multiplexed with analog inputs and analog VREF input. The operation of each pin is selected by clearing/setting the control bits in the ADCON1 register (A/D Control Register1).

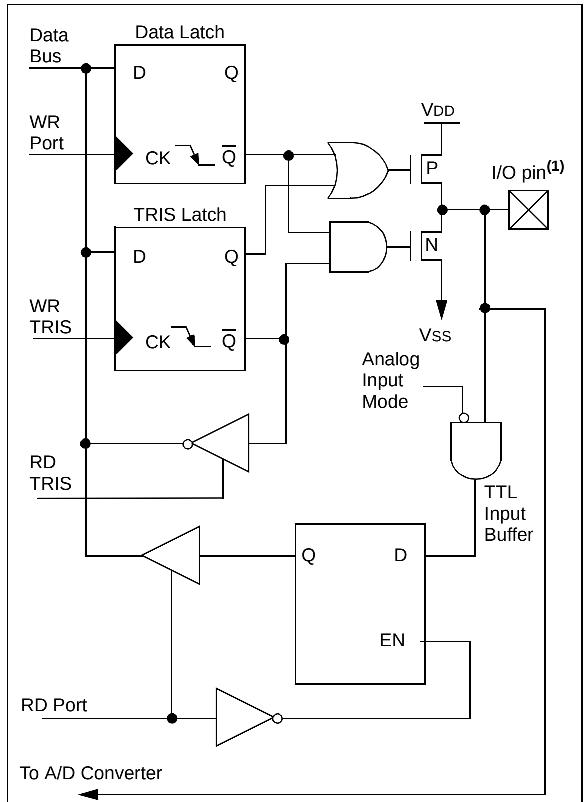
Note:	On a Power-on Reset, these pins are configured as analog inputs and read as '0'.

The TRISA register controls the direction of the RA pins, even when they are being used as analog inputs. The user must ensure the bits in the TRISA register are maintained set when using them as analog inputs.

EXAMPLE 3-1: INITIALIZING PORTA

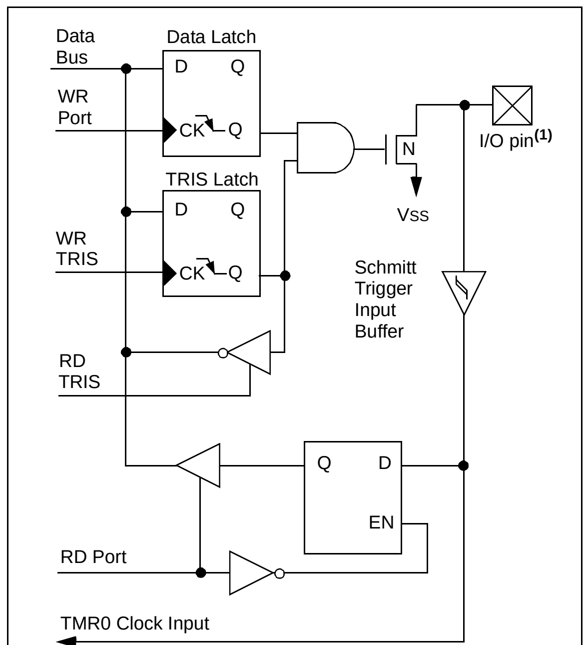
```
BCF     STATUS, RP0   ;
BCF     STATUS, RP1   ; Bank0
CLRF    PORTA         ; Initialize PORTA by
                      ; clearing output
                      ; data latches
BSF     STATUS, RP0   ; Select Bank 1
MOVLW   0x06          ; Configure all pins
MOVWF   ADCON1        ; as digital inputs
MOVLW   0xCF          ; Value used to
                      ; initialize data
                      ; direction
MOVWF   TRISA         ; Set RA<3:0> as inputs
                      ; RA<5:4> as outputs
                      ; TRISA<7:6>are always
                      ; read as '0'.
```

FIGURE 3-1: BLOCK DIAGRAM OF RA3:RA0 AND RA5 PINS



Note 1: I/O pins have protection diodes to VDD and VSS.

FIGURE 3-2: BLOCK DIAGRAM OF RA4/T0CKI PIN



Note 1: I/O pin has protection diodes to Vss only.

TABLE 3-1: PORTA FUNCTIONS

Name	Bit#	Buffer	Function
RA0/AN0	bit0	TTL	Input/output or analog input.
RA1/AN1	bit1	TTL	Input/output or analog input.
RA2/AN2	bit2	TTL	Input/output or analog input.
RA3/AN3/VREF	bit3	TTL	Input/output or analog input or VREF.
RA4/T0CKI	bit4	ST	Input/output or external clock input for Timer0. Output is open drain type.
RA5/$\overline{SS}$/AN4	bit5	TTL	Input/output or slave select input for synchronous serial port or analog input.

Legend: TTL = TTL input, ST = Schmitt Trigger input

TABLE 3-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
05h	PORTA	—	—	RA5	RA4	RA3	RA2	RA1	RA0	--0x 0000	--0u 0000
85h	TRISA	—	—	PORTA Data Direction Register						--11 1111	--11 1111
9Fh	ADCON1	ADFM	—	—	—	PCFG3	PCFG2	PCFG1	PCFG0	--0- 0000	--0- 0000

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'.
Shaded cells are not used by PORTA.

Note:	When using the SSP module in SPI Slave mode and $\overline{SS}$ enabled, the A/D converter must be set to one of the following modes, where PCFG3:PCFG0 = 0100,0101, 011x, 1101, 1110, 1111.

3.3 PORTC and the TRISC Register

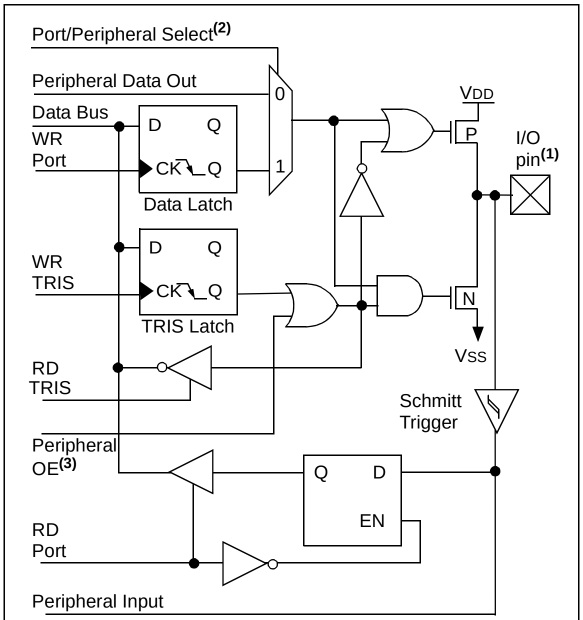
PORTC is an 8-bit wide, bi-directional port. The corresponding data direction register is TRISC. Setting a TRISC bit (= 1) will make the corresponding PORTC pin an input (i.e., put the corresponding output driver in a Hi-Impedance mode). Clearing a TRISC bit (= 0) will make the corresponding PORTC pin an output (i.e., put the contents of the output latch on the selected pin).

PORTC is multiplexed with several peripheral functions (Table 3-5). PORTC pins have Schmitt Trigger input buffers.

When the I^{2}C module is enabled, the PORTC<4:3> pins can be configured with normal I^{2}C levels, or with SMBus levels by using the CKE bit (SSPSTAT<6>).

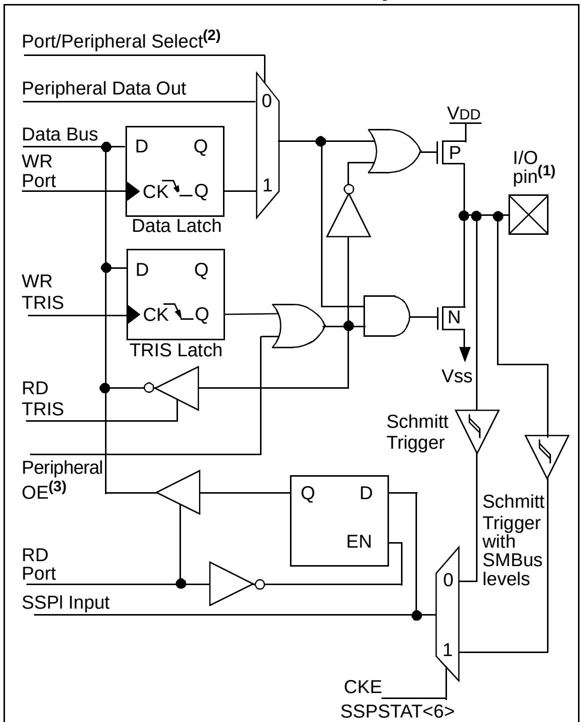
When enabling peripheral functions, care should be taken in defining TRIS bits for each PORTC pin. Some peripherals override the TRIS bit to make a pin an output, while other peripherals override the TRIS bit to make a pin an input. Since the TRIS bit override is in effect while the peripheral is enabled, read-modify-write instructions (`BSF, BCF, XORWF`) with TRISC as destination, should be avoided. The user should refer to the corresponding peripheral section for the correct TRIS bit settings.

FIGURE 3-5: PORTC BLOCK DIAGRAM (PERIPHERAL OUTPUT OVERRIDE) RC<2:0>, RC<7:5>



Note 1: I/O pins have diode protection to V_{DD} and V_{SS}.
2: Port/Peripheral select signal selects between port data and peripheral output.
3: Peripheral OE (output enable) is only activated if peripheral select is active.

FIGURE 3-6: PORTC BLOCK DIAGRAM (PERIPHERAL OUTPUT OVERRIDE) RC<4:3>



Note 1: I/O pins have diode protection to V_{DD} and V_{SS}.
2: Port/Peripheral select signal selects between port data and peripheral output.
3: Peripheral OE (output enable) is only activated if peripheral select is active.

3.5 PORTE and TRISE Register

PORTE and TRISE are not implemented on the PIC16F873 or PIC16F876.

PORTE has three pins (RE0/RD/AN5, RE1/WR/AN6, and RE2/CS/AN7) which are individually configureable as inputs or outputs. These pins have Schmitt Trigger input buffers.

The PORTE pins become the I/O control inputs for the microprocessor port when bit PSPMODE (TRISE<4>) is set. In this mode, the user must make certain that the TRISE<2:0> bits are set, and that the pins are configured as digital inputs. Also ensure that ADCON1 is configured for digital I/O. In this mode, the input buffers are TTL.

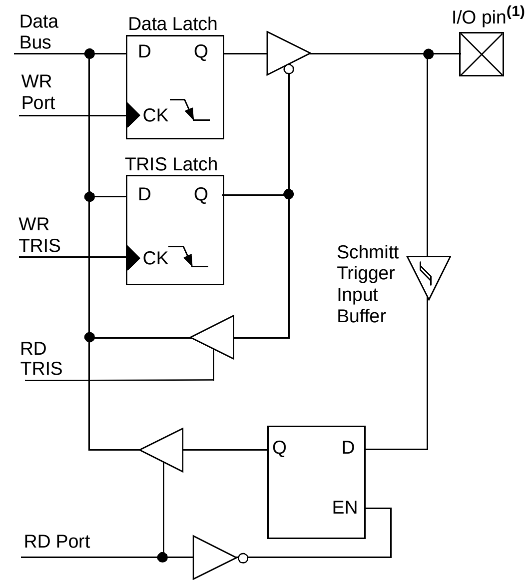
Register 3-1 shows the TRISE register, which also controls the parallel slave port operation.

PORTE pins are multiplexed with analog inputs. When selected for analog input, these pins will read as '0's.

TRISE controls the direction of the RE pins, even when they are being used as analog inputs. The user must make sure to keep the pins configured as inputs when using them as analog inputs.

Note:	On a Power-on Reset, these pins are configured as analog inputs, and read as '0'.

FIGURE 3-8: PORTE BLOCK DIAGRAM (IN I/O PORT MODE)



Note 1: I/O pins have protection diodes to VDD and VSS.

TABLE 3-9: PORTE FUNCTIONS

Name	Bit#	Buffer Type	Function
RE0/RD/AN5	bit0	ST/TTL(1)	I/O port pin or read control input in Parallel Slave Port mode or analog input: RD 1 = Idle 0 = Read operation. Contents of PORTD register are output to PORTD I/O pins (if chip selected)
RE1/WR/AN6	bit1	ST/TTL(1)	I/O port pin or write control input in Parallel Slave Port mode or analog input: WR 1 = Idle 0 = Write operation. Value of PORTD I/O pins is latched into PORTD register (if chip selected)
RE2/CS/AN7	bit2	ST/TTL(1)	I/O port pin or chip select control input in Parallel Slave Port mode or analog input: CS 1 = Device is not selected 0 = Device is selected

Legend: ST = Schmitt Trigger input, TTL = TTL input
Note 1: Input buffers are Schmitt Triggers when in I/O mode and TTL buffers when in Parallel Slave Port mode.

TABLE 3-10: SUMMARY OF REGISTERS ASSOCIATED WITH PORTE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
09h	PORTE	—	—	—	—	—	RE2	RE1	RE0	---- -xxx	---- -uuu
89h	TRISE	IBF	OBF	IBOV	PSPMODE	—	PORTE Data Direction Bits			0000 -111	0000 -111
9Fh	ADCON1	ADFM	—	—	—	PCFG3	PCFG2	PCFG1	PCFG0	--0- 0000	--0- 0000

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by PORTE.

NOTES:

10.2 USART Asynchronous Mode

In this mode, the USART uses standard non-return-to-zero (NRZ) format (one START bit, eight or nine data bits, and one STOP bit). The most common data format is 8-bits. An on-chip, dedicated, 8-bit baud rate generator can be used to derive standard baud rate frequencies from the oscillator. The USART transmits and receives the LSb first. The transmitter and receiver are functionally independent, but use the same data format and baud rate. The baud rate generator produces a clock, either x16 or x64 of the bit shift rate, depending on bit BRGH (TXSTA<2>). Parity is not supported by the hardware, but can be implemented in software (and stored as the ninth data bit). Asynchronous mode is stopped during SLEEP.

Asynchronous mode is selected by clearing bit SYNC (TXSTA<4>).

The USART Asynchronous module consists of the following important elements:

- Baud Rate Generator
- Sampling Circuit
- Asynchronous Transmitter
- Asynchronous Receiver

10.2.1 USART ASYNCHRONOUS TRANSMITTER

The USART transmitter block diagram is shown in Figure 10-1. The heart of the transmitter is the transmit (serial) shift register (TSR). The shift register obtains its data from the read/write transmit buffer, TXREG. The TXREG register is loaded with data in software. The TSR register is not loaded until the STOP bit has been transmitted from the previous load. As soon as the STOP bit is transmitted, the TSR is loaded with new data from the TXREG register (if available). Once the TXREG register transfers the data to the TSR register (occurs in one TCY), the TXREG register is empty and flag bit TXIF (PIR1<4>) is set. This interrupt can be enabled/disabled by setting/clearing enable bit TXIE (PIE1<4>). Flag bit TXIF will be set, regardless of the state of enable bit TXIE and cannot be cleared in software. It will reset only when new data is loaded into the TXREG register. While flag bit TXIF indicates the status of the TXREG register, another bit TRMT (TXSTA<1>) shows the status of the TSR register. Status bit TRMT is a read only bit, which is set when the TSR register is empty. No interrupt logic is tied to this bit, so the user has to poll this bit in order to determine if the TSR register is empty.

Note	
1:	The TSR register is not mapped in data memory, so it is not available to the user.
2:	Flag bit TXIF is set when enable bit TXEN is set. TXIF is cleared by loading TXREG.

Transmission is enabled by setting enable bit TXEN (TXSTA<5>). The actual transmission will not occur until the TXREG register has been loaded with data and the baud rate generator (BRG) has produced a shift clock (Figure 10-2). The transmission can also be started by first loading the TXREG register and then setting enable bit TXEN. Normally, when transmission is first started, the TSR register is empty. At that point, transfer to the TXREG register will result in an immediate transfer to TSR, resulting in an empty TXREG. A back-to-back transfer is thus possible (Figure 10-3). Clearing enable bit TXEN during a transmission will cause the transmission to be aborted and will reset the transmitter. As a result, the RC6/TX/CK pin will revert to hi-impedance.

In order to select 9-bit transmission, transmit bit TX9 (TXSTA<6>) should be set and the ninth bit should be written to TX9D (TXSTA<0>). The ninth bit must be written before writing the 8-bit data to the TXREG register. This is because a data write to the TXREG register can result in an immediate transfer of the data to the TSR register (if the TSR is empty). In such a case, an incorrect ninth data bit may be loaded in the TSR register.

FIGURE 10-1: USART TRANSMIT BLOCK DIAGRAM

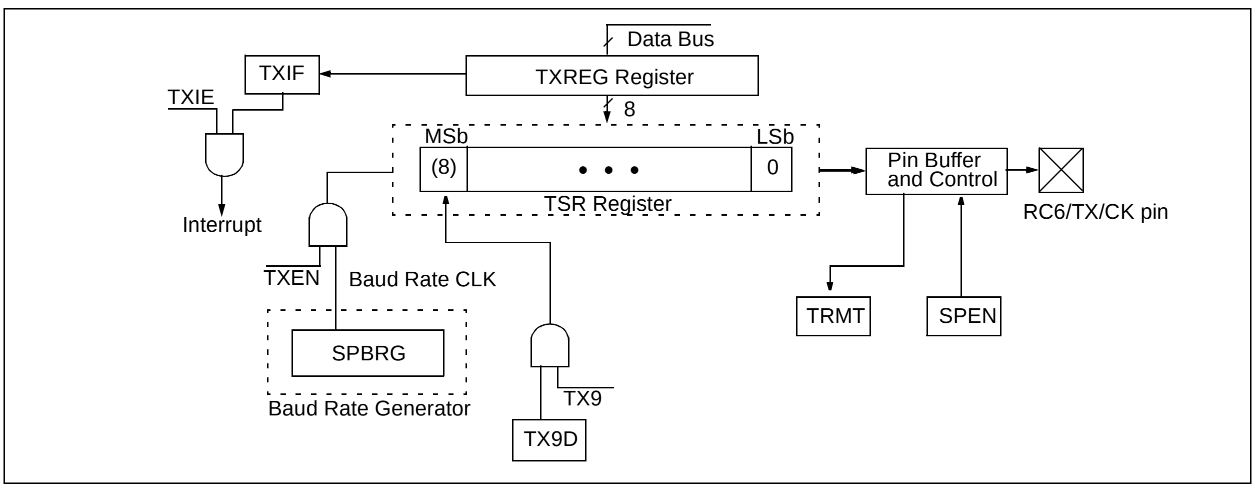
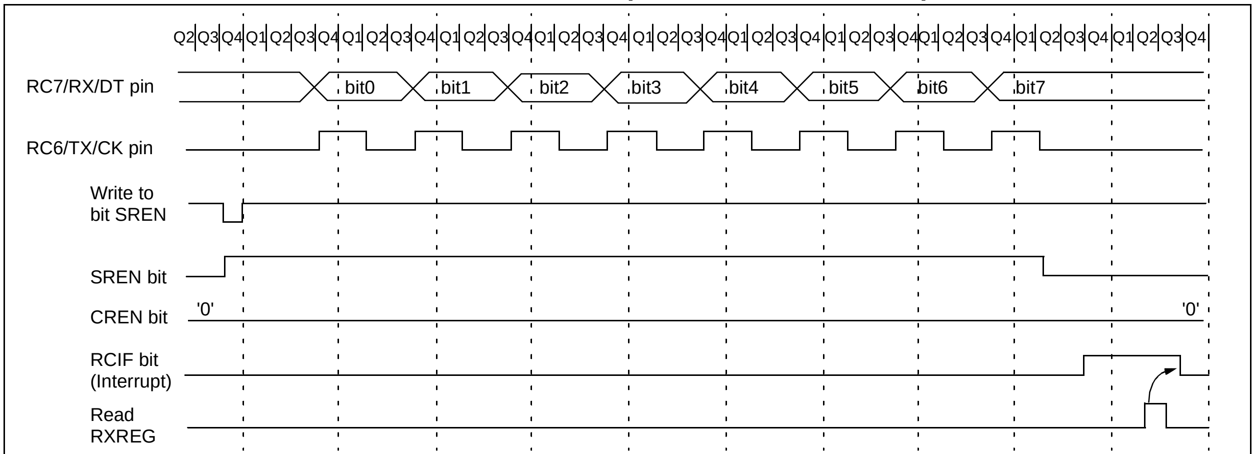


FIGURE 10-11: SYNCHRONOUS RECEPTION (MASTER MODE, SREN)



Note: Timing diagram demonstrates SYNC Master mode with bit SREN = '1' and bit BRG = '0'.

10.4 USART Synchronous Slave Mode

Synchronous Slave mode differs from the Master mode in the fact that the shift clock is supplied externally at the RC6/TX/CK pin (instead of being supplied internally in Master mode). This allows the device to transfer or receive data while in SLEEP mode. Slave mode is entered by clearing bit CSRC (TXSTA<7>).

10.4.1 USART SYNCHRONOUS SLAVE TRANSMIT

The operation of the Synchronous Master and Slave modes is identical, except in the case of the SLEEP mode.

If two words are written to the TXREG and then the `SLEEP` instruction is executed, the following will occur:

a) The first word will immediately transfer to the TSR register and transmit.
b) The second word will remain in TXREG register.
c) Flag bit TXIF will not be set.
d) When the first word has been shifted out of TSR, the TXREG register will transfer the second word to the TSR and flag bit TXIF will now be set.
e) If enable bit TXIE is set, the interrupt will wake the chip from SLEEP and if the global interrupt is enabled, the program will branch to the interrupt vector (0004h).

When setting up a Synchronous Slave Transmission, follow these steps:

1. Enable the synchronous slave serial port by setting bits SYNC and SPEN and clearing bit CSRC.
2. Clear bits CREN and SREN.
3. If interrupts are desired, then set enable bit TXIE.
4. If 9-bit transmission is desired, then set bit TX9.
5. Enable the transmission by setting enable bit TXEN.
6. If 9-bit transmission is selected, the ninth bit should be loaded in bit TX9D.
7. Start transmission by loading data to the TXREG register.
8. If using interrupts, ensure that GIE and PEIE (bits 7 and 6) of the INTCON register are set.

TABLE 10-10: REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE TRANSMISSION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
0Bh, 8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	R0IF	0000 000x	0000 000u
0Ch	PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
19h	TXREG	USART Transmit Register								0000 0000	0000 0000
8Ch	PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented, read as '0'. Shaded cells are not used for synchronous slave transmission.
Note 1: Bits PSPIE and PSPIF are reserved on PIC16F873/876 devices; always maintain these bits clear.

12.13 Power-down Mode (SLEEP)

Power-down mode is entered by executing a `SLEEP` instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the $\overline{\text{PD}}$ bit (STATUS<3>) is cleared, the $\overline{\text{TO}}$ (STATUS<4>) bit is set, and the oscillator driver is turned off. The I/O ports maintain the status they had before the `SLEEP` instruction was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, place all I/O pins at either V_{DD} or V_{SS}, ensure no external circuitry is drawing current from the I/O pin, power-down the A/D and disable external clocks. Pull all I/O pins that are hi-impedance inputs, high or low externally, to avoid switching currents caused by floating inputs. The T0CKI input should also be at V_{DD} or V_{SS} for lowest current consumption. The contribution from on-chip pull-ups on PORTB should also be considered.

The $\overline{\text{MCLR}}$ pin must be at a logic high level (V_{IHMC}).

12.13.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

1. External RESET input on $\overline{\text{MCLR}}$ pin.
2. Watchdog Timer Wake-up (if WDT was enabled).
3. Interrupt from INT pin, RB port change or peripheral interrupt.

External $\overline{\text{MCLR}}$ Reset will cause a device RESET. All other events are considered a continuation of program execution and cause a "wake-up". The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits in the STATUS register can be used to determine the cause of device RESET. The $\overline{\text{PD}}$ bit, which is set on power-up, is cleared when `SLEEP` is invoked. The $\overline{\text{TO}}$ bit is cleared if a WDT time-out occurred and caused wake-up.

The following peripheral interrupts can wake the device from SLEEP:

1. PSP read or write (PIC16F874/877 only).
2. TMR1 interrupt. Timer1 must be operating as an asynchronous counter.
3. CCP Capture mode interrupt.
4. Special event trigger (Timer1 in Asynchronous mode using an external clock).
5. SSP (START/STOP) bit detect interrupt.
6. SSP transmit or receive in Slave mode (SPI/I^2C).
7. USART RX or TX (Synchronous Slave mode).
8. A/D conversion (when A/D clock source is RC).
9. EEPROM write operation completion

Other peripherals cannot generate interrupts since during SLEEP, no on-chip clocks are present.

When the `SLEEP` instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the `SLEEP` instruction. If the GIE bit is set (enabled), the device executes the instruction after the `SLEEP` instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following `SLEEP` is not desirable, the user should have a `NOP` after the `SLEEP` instruction.

12.13.2 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a `SLEEP` instruction, the `SLEEP` instruction will complete as a `NOP`. Therefore, the WDT and WDT postscaler will not be cleared, the $\overline{\text{TO}}$ bit will not be set and $\overline{\text{PD}}$ bits will not be cleared.
- If the interrupt occurs **during or after** the execution of a `SLEEP` instruction, the device will immediately wake-up from SLEEP. The `SLEEP` instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the $\overline{\text{TO}}$ bit will be set and the $\overline{\text{PD}}$ bit will be cleared.

Even if the flag bits were checked before executing a `SLEEP` instruction, it may be possible for flag bits to become set before the `SLEEP` instruction completes. To determine whether a `SLEEP` instruction executed, test the $\overline{\text{PD}}$ bit. If the $\overline{\text{PD}}$ bit is set, the `SLEEP` instruction was executed as a `NOP`.

To ensure that the WDT is cleared, a `CLRWDT` instruction should be executed before a `SLEEP` instruction.

13.1 Instruction Descriptions

ADDLW	Add Literal and W
Syntax:	[*label*] ADDLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) + k → (W)
Status Affected:	C, DC, Z
Description:	The contents of the W register are added to the eight bit literal 'k' and the result is placed in the W register.

ADDWF	Add W and f
Syntax:	[*label*] ADDWF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) + (f) → (destination)
Status Affected:	C, DC, Z
Description:	Add the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

ANDLW	AND Literal with W
Syntax:	[*label*] ANDLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) .AND. (k) → (W)
Status Affected:	Z
Description:	The contents of W register are AND'ed with the eight bit literal 'k'. The result is placed in the W register.

ANDWF	AND W with f
Syntax:	[*label*] ANDWF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) .AND. (f) → (destination)
Status Affected:	Z
Description:	AND the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

BCF	Bit Clear f
Syntax:	[*label*] BCF f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	0 → (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is cleared.

BSF	Bit Set f
Syntax:	[*label*] BSF f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	1 → (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is set.

BTFSS	Bit Test f, Skip if Set
Syntax:	[*label*] BTFSS f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b < 7
Operation:	skip if (f<b>) = 1
Status Affected:	None
Description:	If bit 'b' in register 'f' is '0', the next instruction is executed. If bit 'b' is '1', then the next instruction is discarded and a `NOP` is executed instead, making this a $2T_{CY}$ instruction.

BTFSC	Bit Test, Skip if Clear
Syntax:	[*label*] BTFSC f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	skip if (f<b>) = 0
Status Affected:	None
Description:	If bit 'b' in register 'f' is '1', the next instruction is executed. If bit 'b', in register 'f', is '0', the next instruction is discarded, and a `NOP` is executed instead, making this a $2T_{CY}$ instruction.

15.1 DC Characteristics: PIC16F873/874/876/877-04 (Commercial, Industrial) PIC16F873/874/876/877-20 (Commercial, Industrial) PIC16LF873/874/876/877-04 (Commercial, Industrial)

PIC16LF873/874/876/877-04 (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial; 0°C ≤ TA ≤ +70°C for commercial				
PIC16F873/874/876/877-04 **PIC16F873/874/876/877-20** (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial; 0°C ≤ TA ≤ +70°C for commercial				
Param No.	**Symbol**	**Characteristic/ Device**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VDD	**Supply Voltage**					
D001		16LF87X	2.0	—	5.5	V	LP, XT, RC osc configuration (DC to 4 MHz)
D001		16F87X	4.0	—	5.5	V	LP, XT, RC osc configuration
D001A			4.5		5.5	V	HS osc configuration
			VBOR		5.5	V	BOR enabled, FMAX = 14 MHz(7)
D002	VDR	**RAM Data Retention Voltage(1)**	—	1.5	—	V	
D003	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	—	—	V/ms	See section on Power-on Reset for details
D005	VBOR	**Brown-out Reset Voltage**	3.7	4.0	4.35	V	BODEN bit in configuration word enabled

Legend: Rows with standard voltage device data only are shaded for improved readability.

† Data in “Typ” column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading, switching rate, oscillator type, internal code execution pattern and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD;
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

7: When BOR is enabled, the device will operate correctly until the VBOR voltage trip point is reached.

FIGURE 15-6: EXTERNAL CLOCK TIMING

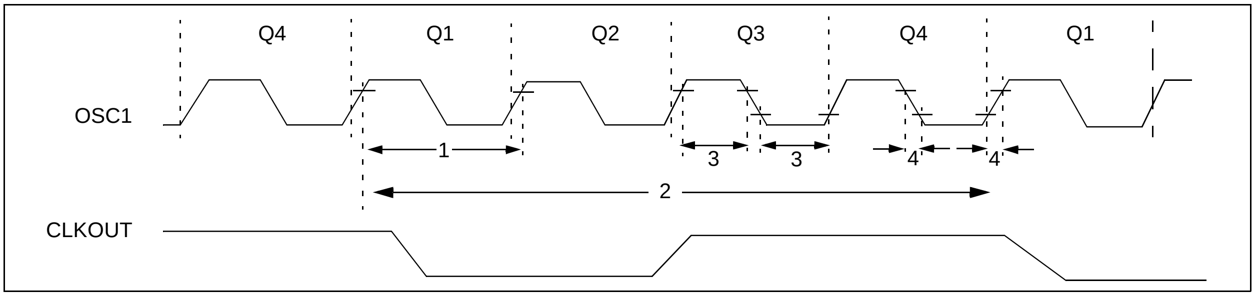


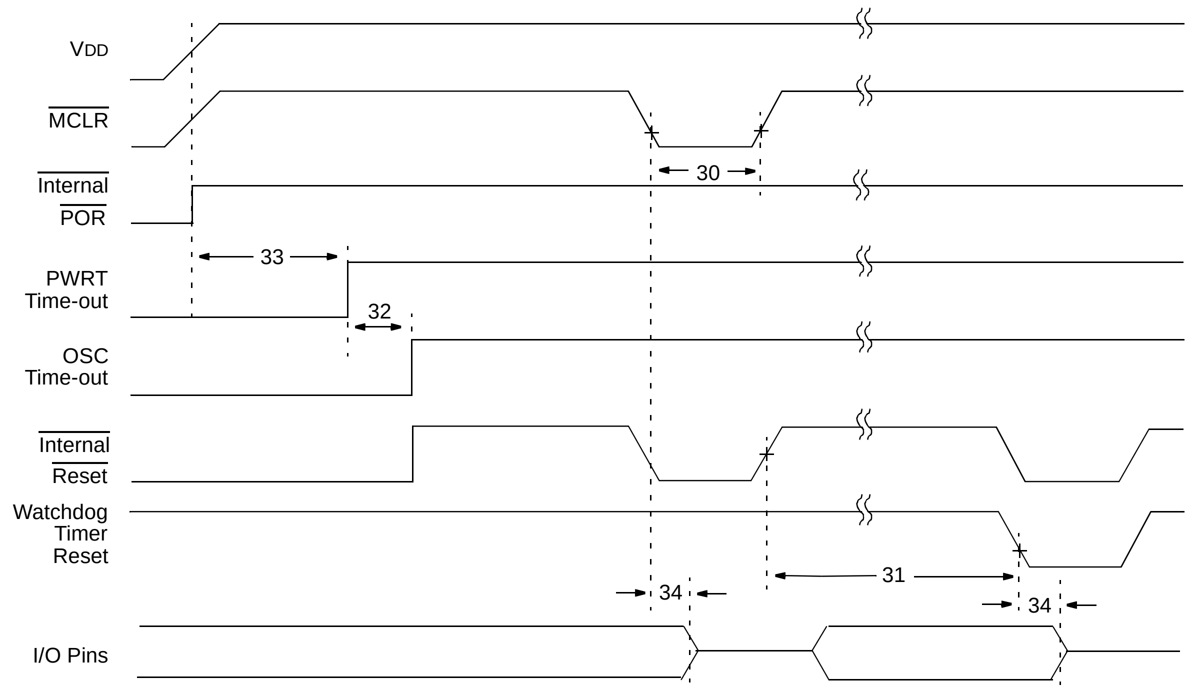
TABLE 15-1: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	FOSC	External CLKIN Frequency	DC	—	4	MHz	XT and RC osc mode
		(Note 1)	DC	—	4	MHz	HS osc mode (-04)
			DC	—	10	MHz	HS osc mode (-10)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency	DC	—	4	MHz	RC osc mode
		(Note 1)	0.1	—	4	MHz	XT osc mode
			4	—	10	MHz	HS osc mode (-10)
			4	—	20	MHz	HS osc mode (-20)
			5	—	200	kHz	LP osc mode
1	TOSC	External CLKIN Period	250	—	—	ns	XT and RC osc mode
		(Note 1)	250	—	—	ns	HS osc mode (-04)
			100	—	—	ns	HS osc mode (-10)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
		Oscillator Period	250	—	—	ns	RC osc mode
		(Note 1)	250	—	10,000	ns	XT osc mode
			250	—	—	ns	HS osc mode (-04)
			100	—	250	ns	HS osc mode (-10)
			50	—	250	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
2	TCY	Instruction Cycle Time **(Note 1)**	200	TCY	DC	ns	TCY = 4/FOSC
3	TosL, TosH	External Clock in (OSC1) High or Low Time	100	—	—	ns	XT oscillator
			2.5	—	—	μs	LP oscillator
			15	—	—	ns	HS oscillator
4	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions, with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "max." cycle time limit is "DC" (no clock) for all devices.

FIGURE 15-8: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



Note: Refer to Figure 15-5 for load conditions.

FIGURE 15-9: BROWN-OUT RESET TIMING

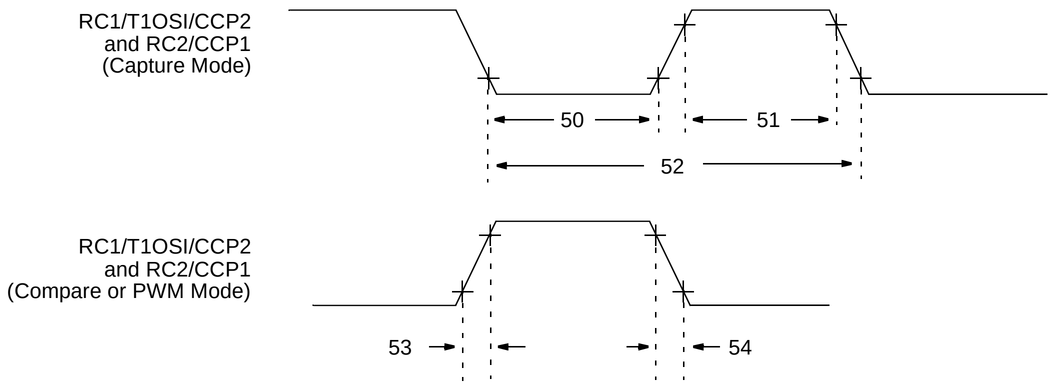
TABLE 15-3: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER, AND BROWN-OUT RESET REQUIREMENTS

Parameter No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	2	—	—	μs	VDD = 5V, -40°C to +85°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +85°C
32	Tost	Oscillation Start-up Timer Period	—	1024 TOSC	—	—	TOSC = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +85°C
34	TIOZ	I/O Hi-impedance from MCLR Low or Watchdog Timer Reset	—	—	2.1	μs	
35	TBOR	Brown-out Reset pulse width	100	—	—	μs	VDD ≤ VBOR (D005)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 15-11: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)



Note: Refer to Figure 15-5 for load conditions.

TABLE 15-5: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1 AND CCP2)

Param No.	Sym	Characteristic			Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 and CCP2 input low time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	Standard(**F**)	10	—	—	ns	
				Extended(**LF**)	20	—	—	ns	
51*	TccH	CCP1 and CCP2 input high time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	Standard(**F**)	10	—	—	ns	
				Extended(**LF**)	20	—	—	ns	
52*	TccP	CCP1 and CCP2 input period			$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1, 4 or 16)
53*	TccR	CCP1 and CCP2 output rise time		Standard(**F**)	—	10	25	ns	
				Extended(**LF**)	—	25	50	ns	
54*	TccF	CCP1 and CCP2 output fall time		Standard(**F**)	—	10	25	ns	
				Extended(**LF**)	—	25	45	ns	

* These parameters are characterized but not tested.
† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

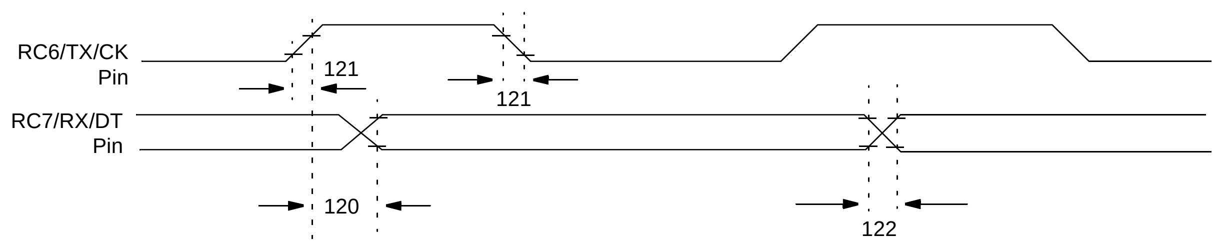
TABLE 15-9: I^2C BUS DATA REQUIREMENTS

Param No.	Sym	Characteristic		Min	Max	Units	Conditions
100	Thigh	Clock high time	100 kHz mode	4.0	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	μs	Device must operate at a minimum of 10 MHz
			SSP Module	0.5TCY	—		
101	Tlow	Clock low time	100 kHz mode	4.7	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	μs	Device must operate at a minimum of 10 MHz
			SSP Module	0.5TCY	—		
102	Tr	SDA and SCL rise time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10 to 400 pF
103	Tf	SDA and SCL fall time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10 to 400 pF
90	Tsu:sta	START condition setup time	100 kHz mode	4.7	—	μs	Only relevant for Repeated START condition
			400 kHz mode	0.6	—	μs	
91	Thd:sta	START condition hold time	100 kHz mode	4.0	—	μs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	μs	
106	Thd:dat	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
107	Tsu:dat	Data input setup time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
92	Tsu:sto	STOP condition setup time	100 kHz mode	4.7	—	μs	
			400 kHz mode	0.6	—	μs	
109	Taa	Output valid from clock	100 kHz mode	—	3500	ns	**(Note 1)**
			400 kHz mode	—	—	ns	
110	Tbuf	Bus free time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
	Cb	Bus capacitive loading		—	400	pF	

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

2: A fast mode (400 kHz) I^2C bus device can be used in a standard mode (100 kHz) I^2C bus system, but the requirement that Tsu:dat ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line TR max.+ Tsu:dat = 1000 + 250 = 1250 ns (according to the standard mode I^2C bus specification) before the SCL line is released.

FIGURE 15-19: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING



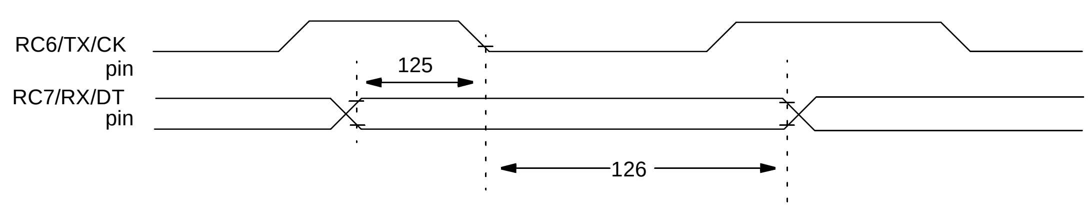
Note: Refer to Figure 15-5 for load conditions.

TABLE 15-10: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
120	TckH2dtV	SYNC XMIT (MASTER & SLAVE) Clock high to data out valid	Standard(**F**)	—	—	80	ns	
			Extended(**LF**)	—	—	100	ns	
121	Tckrf	Clock out rise time and fall time (Master mode)	Standard(**F**)	—	—	45	ns	
			Extended(**LF**)	—	—	50	ns	
122	Tdtrf	Data out rise time and fall time	Standard(**F**)	—	—	45	ns	
			Extended(**LF**)	—	—	50	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 15-20: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



Note: Refer to Figure 15-5 for load conditions.

TABLE 15-11: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
125	TdtV2ckL	SYNC RCV (MASTER & SLAVE) Data setup before CK ↓ (DT setup time)	15	—	—	ns	
126	TckL2dtl	Data hold after CK ↓ (DT hold time)	15	—	—	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

TABLE 15-12: PIC16F87X-04 (COMMERCIAL, INDUSTRIAL, EXTENDED) PIC16F87X-10 (EXTENDED) PIC16F87X-20 (COMMERCIAL, INDUSTRIAL) PIC16LF87X-04 (COMMERCIAL, INDUSTRIAL)

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
A01	NR	Resolution		—	—	10-bits	bit	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A03	EIL	Integral linearity error		—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A04	EDL	Differential linearity error		—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A06	EOFF	Offset error		—	—	< ± 2	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A07	EGN	Gain error		—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A10	—	Monotonicity(3)		—	guaranteed	—	—	VSS ≤ VAIN ≤ VREF
A20	VREF	Reference voltage (VREF+ - VREF-)		2.0	—	VDD + 0.3	V	Absolute minimum electrical spec. To ensure 10-bit accuracy.
A21	VREF+	Reference voltage High		AVDD - 2.5V		AVDD + 0.3V	V	
A22	VREF-	Reference voltage low		AVSS - 0.3V		VREF+ - 2.0V	V	
A25	VAIN	Analog input voltage		VSS - 0.3 V	—	VREF + 0.3 V	V	
A30	ZAIN	Recommended impedance of analog voltage source		—	—	10.0	kΩ	
A40	IAD	A/D conversion current (VDD)	Standard	—	220	—	μA	Average current consumption when A/D is on **(Note 1)**
			Extended	—	90	—	μA	
A50	IREF	VREF input current **(Note 2)**		10	—	1000	μA	During VAIN acquisition. Based on differential of VHOLD to VAIN to charge CHOLD, see Section 11.1.
				—	—	10	μA	During A/D Conversion cycle

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

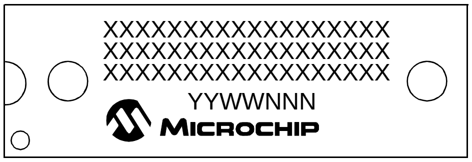
Note 1: When A/D is off, it will not consume any current other than minor leakage current. The power-down current spec includes any such leakage from the A/D module.

2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.

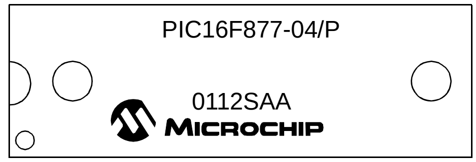
3: The A/D conversion result never decreases with an increase in the input voltage, and has no missing codes.

Package Marking Information (Cont'd)

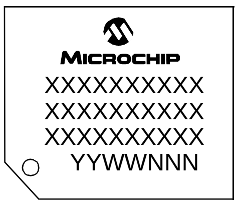
40-Lead PDIP



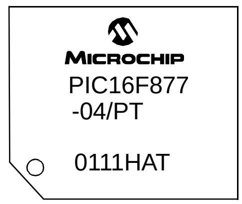
Example



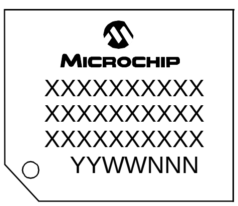
44-Lead TQFP



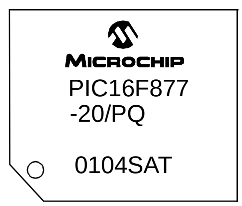
Example



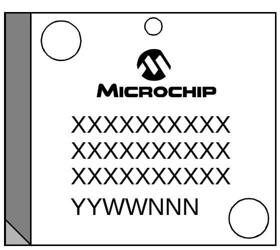
44-Lead MQFP



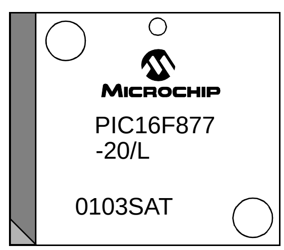
Example



44-Lead PLCC

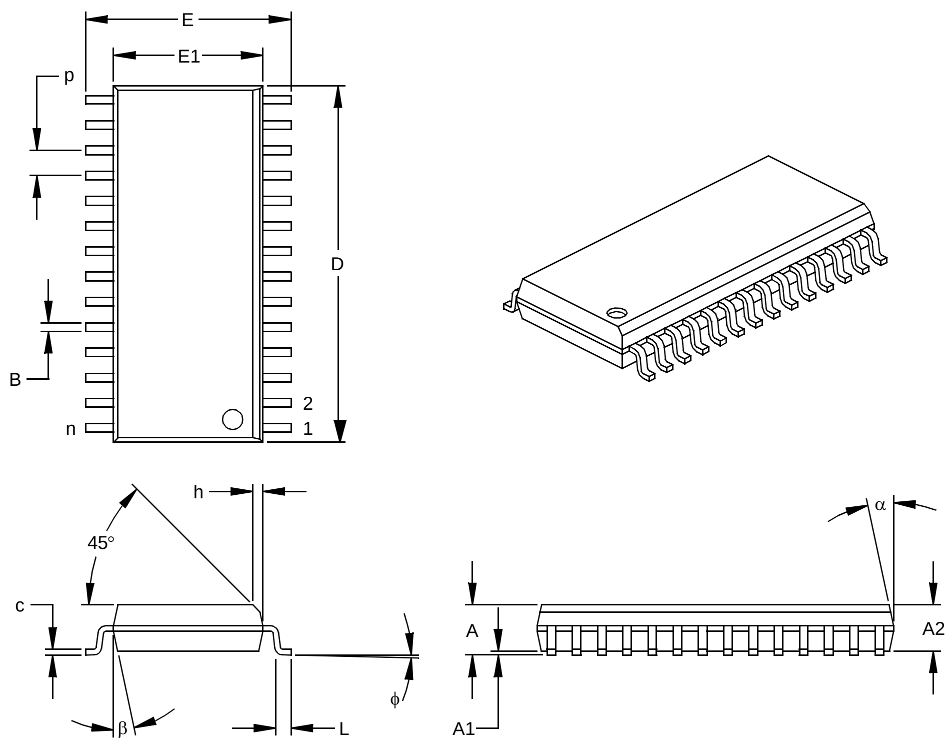


Example



28-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.288	.295	.299	7.32	7.49	7.59
Overall Length	D	.695	.704	.712	17.65	17.87	18.08
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle Top	ϕ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.013	0.23	0.28	0.33
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.
JEDEC Equivalent: MS-013
Drawing No. C04-052

